

## LMS4684 0.5Ω Low-Voltage, Dual SPDT Analog Switch

Check for Samples: [LMS4684](#)

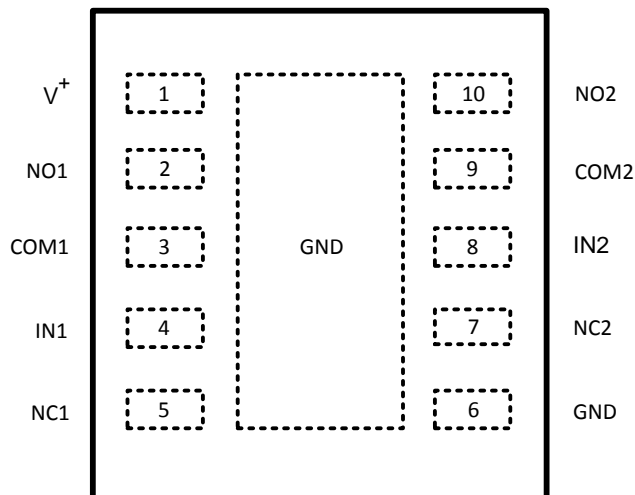
### FEATURES

- NC Switch  $R_{ON}$  0.5Ω max @ 2.7V
- NO Switch  $R_{ON}$  0.8Ω max @ 2.7V
- 5 nA (typ) Supply Current  $T_A = 25^{\circ}\text{C}$
- 1.8 to 5.5V Single Supply Operation
- 12-Bump DSBGA Package
- WSON-10 Package, 3x4mm

### APPLICATIONS

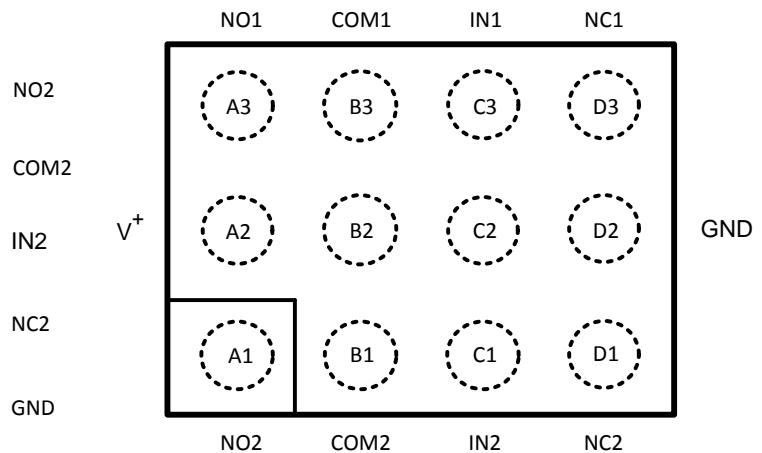
- Power Routing
- Battery-Operated Equipment
- Communications Circuits
- Modems
- Cell Phones

### Connection Diagram



Exposed pad on back of package needs to be connected to pin 6 on the board

**Figure 1. 10-WSON Package-Top View**



Center Bumps B2 and C2 are Not Electrically Connected

**Figure 2. 12-Bump DSBGA Package-Top View (Bumped Side Down)**



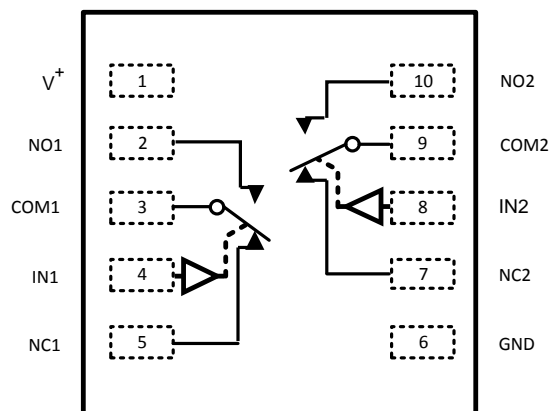
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 2004–2013, Texas Instruments Incorporated

## SCHEMATIC DIAGRAM



IN	NO	NC
0	Off	On
1	On	Off
Switches shown for Logic "0" input		

## PIN DESCRIPTIONS

Name	Pin ID		Description
	WSO	DSBGA	
NC	5, 7	D3, D1	Analog switch normally closed terminal
IN	4, 8	C3, C1	Digital control input
COM	3, 9	B3, B1	Analog switch common terminal
NO	2, 10	A3, A1	Analog switch normally open terminal
V <sup>+</sup>	1	A2	Positive supply voltage
GND	6	D2	Ground
		B2, C2	Not electrically connected. Can be used to help dissipate heat by connecting to GND pin.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## ABSOLUTE MAXIMUM RATINGS <sup>(1)(2)(3)</sup>

V <sup>+</sup>	–0.3V to 6.0V	
IN	–0.3V to 6.0V	
COM, NO, NC	–0.3V to (V <sup>+</sup> + 0.3V)	
Continuous Switch Current	±400 mA	
ESD Tolerance <sup>(4)</sup>	Human Body Model	2000V
	Machine Model	200V
Storage Temperature Range	–65°C to 150°C	
Junction Temperature <sup>(5)</sup>	150°C Max	

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed.
- (2) All voltages are with respect to GND, unless otherwise specified.
- (3) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (4) Human body model: 1.5 kΩ in series with 100 pF. Machine model, 0Ω in series with 200 pF.
- (5) The maximum power dissipation is a function of T<sub>J(max)</sub>, θ<sub>JA</sub> and T<sub>A</sub>.

## OPERATING RATINGS

Nominal Supply Voltage	1.8V to 5.5V
IN Voltage (regardless of supply)	–0.3V to 5.5V
Temperature Range	–40°C to 85°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed.
- (2) All voltages are with respect to GND, unless otherwise specified.

## PACKAGE THERMAL RESISTANCE

Package	$\theta_{JA}$
WSO-10	43°C / W
DSBGA-12	57°C / W

## ELECTRICAL CHARACTERISTICS

Unless otherwise specified,  $V^+ = 2.7$  to  $3.3V$ ,  $V_{IH} = 1.4V$ ,  $V_{IL} = 0.5V$ . Typical values are measured at  $3V$ , and  $T_J = 25^\circ C$ .

**Boldface** limits apply at temperature extremes.

Symbol	Parameter	Conditions		Min	Typ	Max	Units
$V_{NO}, V_{NC}, V_{COM}$	Analog Signal Range			0		$V^+$	V
$R_{ON} (NC)$	NC On-Resistance <sup>(1)</sup>	$V^+ = 2.7V, I_{COM} = 100\text{ mA}, V_{NC} = 0\text{ to }V^+$			0.3	<b>0.5</b>	$\Omega$
$R_{ON} (NO)$	NO On-Resistance <sup>(1)</sup>	$V^+ = 2.7V, I_{COM} = 100\text{ mA}, V_{NO} = 0\text{ to }V^+$			0.45	<b>0.8</b>	$\Omega$
$\Delta R_{ON}$	On-Resistance Match Between Channels <sup>(1), (2)</sup>	$V^+ = 2.7V, I_{COM} = 100\text{ mA}, V_{NC}\text{ or }V_{NO} = 1.5V$			1.11	<b>60</b>	m $\Omega$
$R_{FLAT}(NC)$	NC-On-Resistance Flatness <sup>(3)</sup>	$V^+ = 2.7V, I_{COM} = 100\text{ mA}, V_{NC} = 0\text{ to }V^+$	WSON $T_J = -40^{\circ}C\text{ to }85^{\circ}C$		0.1	0.25	$\Omega$
			DSBGA $T_J = -40^{\circ}C\text{ to }85^{\circ}C$		0.1	0.25	
$R_{FLAT}(NO)$	NO On-Resistance Flatness <sup>(3)</sup>	$V^+ = 2.7V, I_{COM} = 100\text{ mA}, V_{NO} = 0\text{ to }V^+$			0.18	<b>0.35</b>	$\Omega$
$I_{NO(OFF)}\text{ or }I_{NC(OFF)}$	NO or NC Off Leakage Current	$V^+ = 3.3V, V_{NO}\text{ or }V_{NC} = 3V, 0.3V; V_{COM} = 0.3V, 3V$		-1	0.014	1	nA
				<b>-10</b>		<b>10</b>	
$I_{COM} (ON)$	COM On Leakage Current	$V^+ = 3.3V, V_{NO}\text{ or }V_{NC} = 3V, 0.3V, \text{ or floating}; V_{COM} = 3V, \text{ or floating}$		-2		2	nA
				<b>-20</b>		<b>20</b>	
Dynamic Characteristics							
$t_{ON}$	Turn-On Time	$V^+ = 2.7V, V_{NO}\text{ or }V_{NC} = 1.5V; R_L = 50\Omega; C_L = 35\text{ pF};$			38	60	ns
						<b>70</b>	
$t_{OFF}$	Turn-Off Time	$V^+ = 2.7V, V_{NO}\text{ or }V_{NC} = 1.5V; R_L = 50\Omega; C_L = 35\text{ pF};$			22	40	ns
						<b>50</b>	
$t_{BBM}$	Break-Before-Make Delay	$V^+ = 2.7V, V_{NO}\text{ or }V_{NC} = 1.5V; R_L = 50\Omega; C_L = 35\text{ pF};$		<b>2</b>	15		ns
Q	Charge Injection	COM = 0; $R_S = 0; C_L = 1\text{ nF};$			200		pC
$V_{ISO}$	Off-Isolation <sup>(4)</sup>	$R_L = 50\Omega; C_L = 5\text{ pF}; f = 100\text{ kHz}$			-68		dB
$V_{CT}$	Crosstalk				-72		dB
Digital I/O							
$V_{IH}$	Input Logic High			<b>1.4</b>			V
$V_{IL}$	Input Logic Low					<b>0.5</b>	V

- (1) Guaranteed by design.
- (2)  $\Delta R_{ON}$  is equal to the difference between NC1/NC2  $R_{ON}$  or NO1/NO2  $R_{ON}$  at a specified voltage.
- (3) Flatness is defined as the difference between the maximum and minimum value of on-resistance as measured over the specified analog signal ranges.
- (4) Off-isolation =  $20 \log_{10}(V_{COM}/V_{NO})$ , where  $V_{COM}$  = output,  $V_{NO}$  = input switch off.

## ELECTRICAL CHARACTERISTICS (continued)

Unless otherwise specified,  $V^+ = 2.7$  to  $3.3\text{V}$ ,  $V_{IH} = 1.4\text{V}$ ,  $V_{IL} = 0.5\text{V}$ . Typical values are measured at  $3\text{V}$ , and  $T_J = 25^\circ\text{C}$ .

**Boldface** limits apply at temperature extremes.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$I_{IN}$	IN Input Leakage Current	$V_{IN} = 0$ or $V^+$	<b>-1</b>		<b>1</b>	$\mu\text{A}$
<b>Power Supply</b>						
$V^+$	Power-Supply Range		<b>1.8</b>		<b>5.5</b>	V
$I^+$	Supply Current	$V^+ = 5.5\text{V}$		5		nA

## PARAMETRIC MEASUREMENT INFORMATION

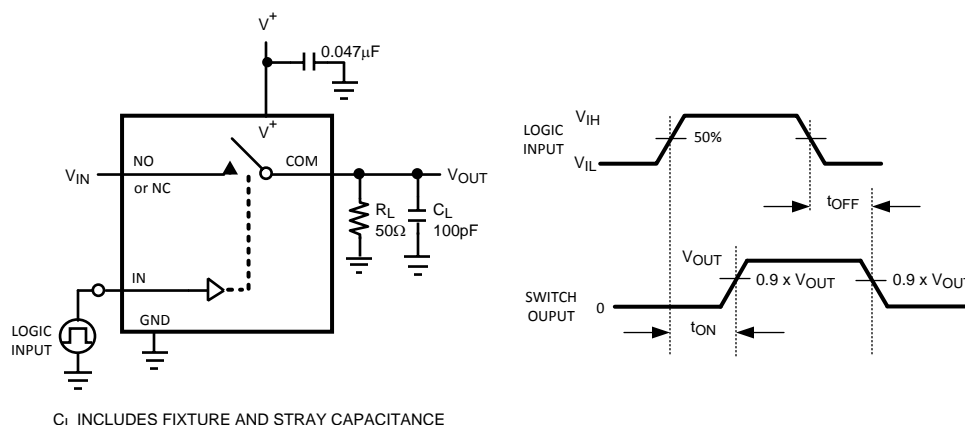


Figure 3.  $t_{ON} / t_{OFF}$  Time

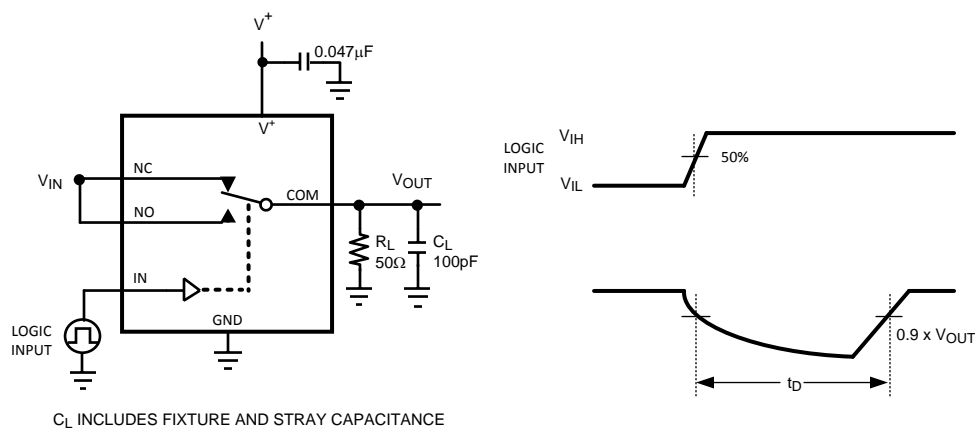


Figure 4. Break-Before Make Delay

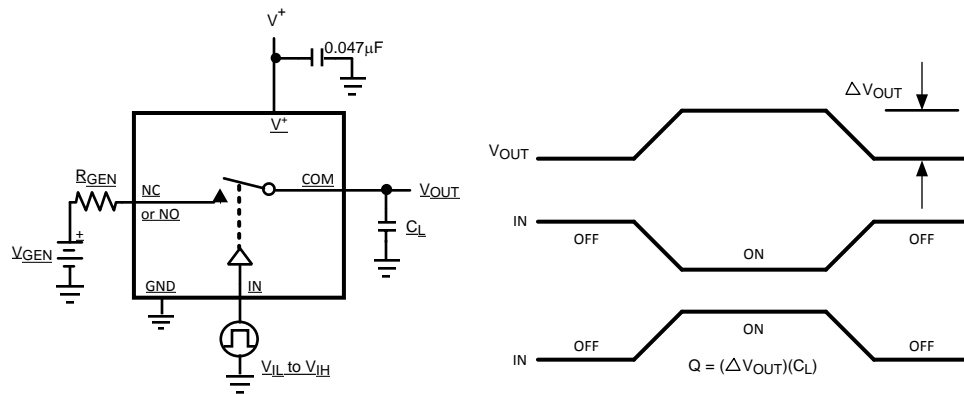


Figure 5. Charge Injection

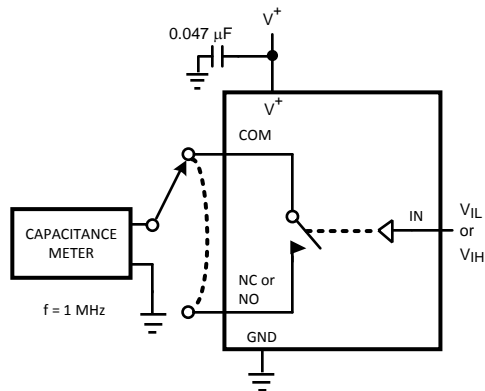


Figure 6. Channel Capacitance

## TYPICAL PERFORMANCE CHARACTERISTICS

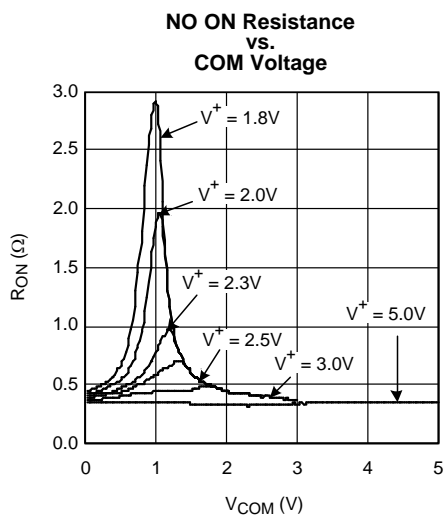


Figure 7.

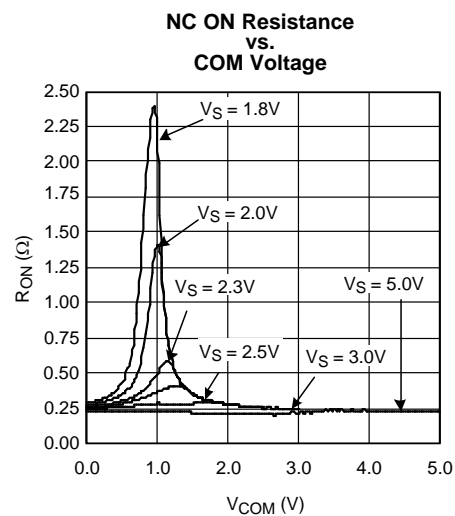


Figure 8.

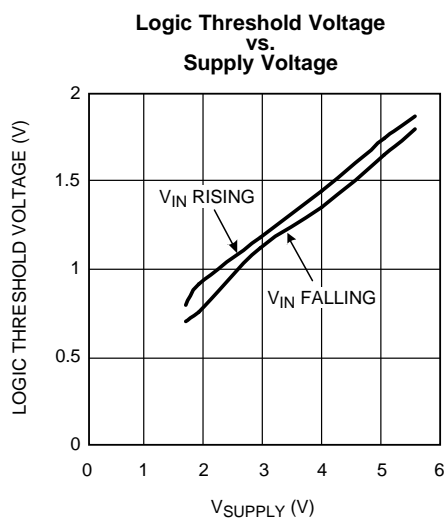


Figure 9.

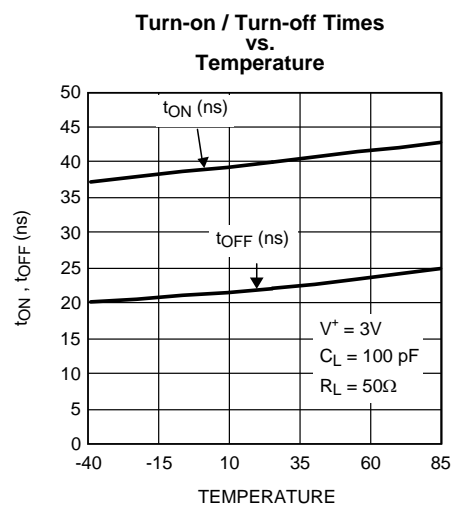


Figure 10.

## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

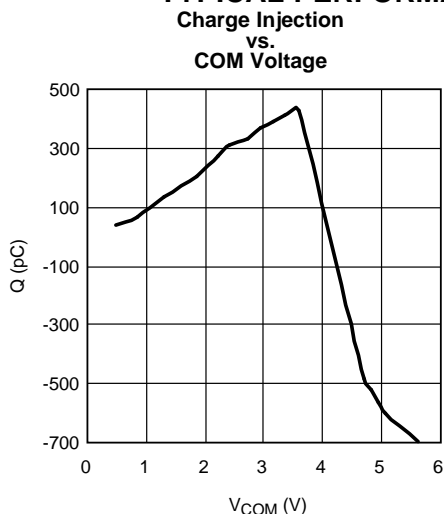


Figure 11.

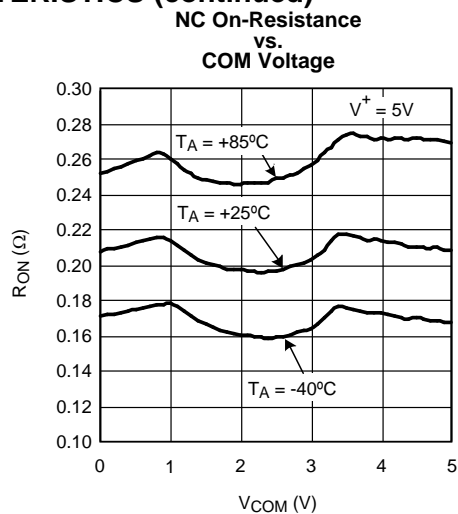


Figure 12.

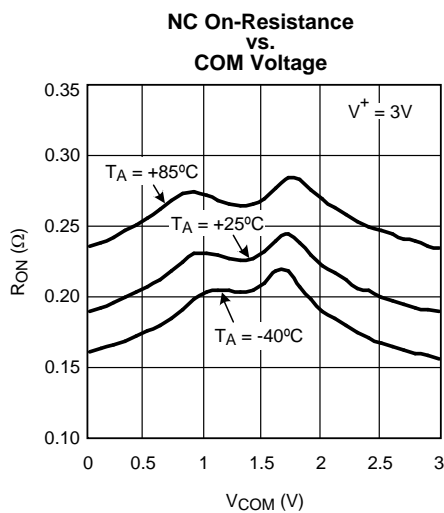


Figure 13.

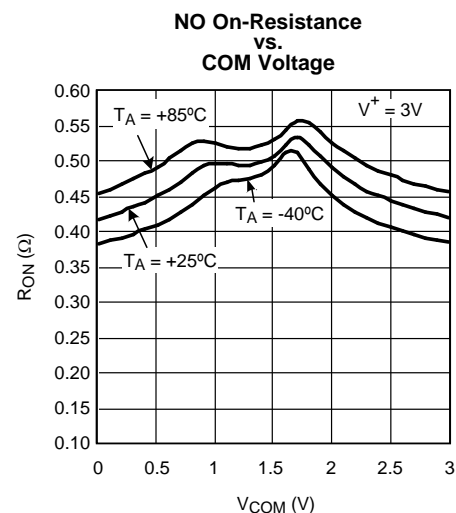


Figure 14.

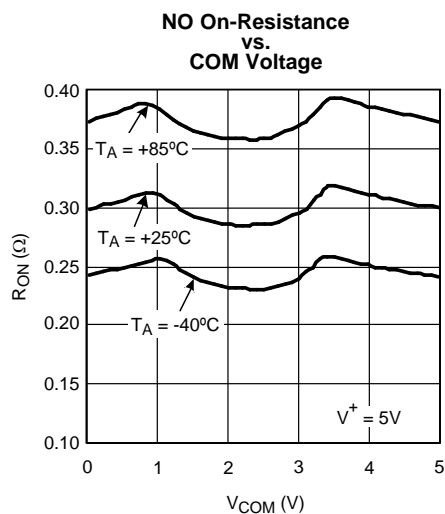


Figure 15.

## FUNCTIONAL DESCRIPTION

The LMS4684 is a low voltage dual, extremely low On-Resistance analog switch that can operate over a supply voltage range of 1.8V to 5.5V. The LMS4684 has been fully characterized to operate in applications with 3V nominal supply voltage and features very low on resistance and fast Turn-Off and Turn-On times with break-before-make switching.

The switch operates asymmetrically; one terminal is normally closed (NC) and the other terminal normally open (NO).

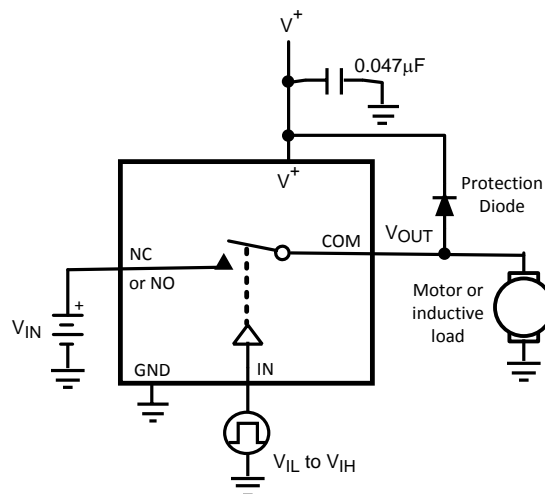
Both NC and NO terminals are connected to a common terminal (COM). This configuration is ideal for applications with asymmetric loads such as speaker handsets and internal speakers.

## Applications Information

### ANALOG INPUT SIGNAL

Analog input signals can range from GND to  $V^+$  and are passed through the switch with very little change. Each switch is bidirectional so any pin can be an input or output.

Exercise care when making connection to an inductive load, such as a motor. As is true with any analog switch used with an inductive load, the back emf produced when the switch is turned off can damage the LMS4684 by electrical overstress. For such applications, a diode should be connected across the motor to prevent damage to the switch, as indicated in [Figure 16](#). Be sure the diode has adequate current carrying capabilities.



**Figure 16. Inductive Load Over-Voltage Protection**

### DIGITAL CONTROL INPUTS

The IN pin can be driven to 5.5V regardless of the voltage level of the supply pin  $V^+$ . For example, if the LMS4684 is operated with a supply of 2V, the digital control input could still be driven to 5V. Power consumption is increased when the control pin is driven rail-to-rail.

### SUPPLY VOLTAGE

It is good general practice to first apply the supply voltage to a CMOS device before driving any other pins. This is also true for the LMS4684 analog switch, which is a CMOS device.

However, if it is necessary to have an analog signal applied before the supply voltage is applied and the analog signal source is not limited to 20 mA max, a diode connected between the supply voltage and the  $V^+$  pin as shown in [Figure 17](#) will provide input protection. This will limit the max analog voltage to a diode drop below  $V^+$ . This diode, D1, will also provide protection against some over voltage situations.



It is also good practice to provide adequate supply bypassing to all analog circuits. We recommend a that minimum bypass capacitor value of  $0.047\mu\text{F}$  be provided for the LMS4684. An inadequate bypass capacitor can lead to excessive supply current.

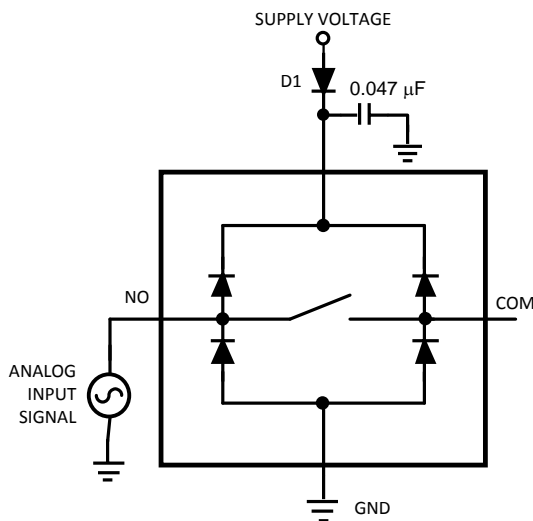


Figure 17. Input Over Voltage Protection Circuitry

## OFF-ISOLATION

Analog switches are composed of FETs (field Effect Transistors). The channel resistance is low when the pass transistors are "on" and that resistance is high when the pass transistors are "off". However, when the pass transistors are "off", the source to drain capacitance of the pass transistors will pass some energy. This capacitance is inversely proportional to the switch "on" resistance, so a switch with a low "on" resistance may not be suitable for some high frequency applications.

Figure 18 shows the equivalent circuit of an analog switch. Unless the load impedance after the switch is relatively low, the switch capacitance will couple excessive energy across the "open" switch at higher frequencies, degrading off isolation performance. Off Isolation of the LMS4684 is specified with a  $50\Omega$  load. Higher load impedances will degrade off isolation performance compared with what is specified.

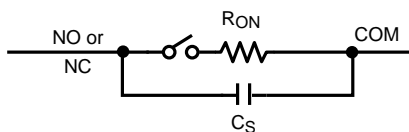
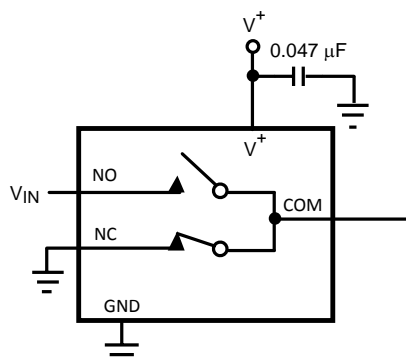


Figure 18. Equivalent Circuit of an Analog Switch

Off isolation may be improved by decreasing the LMS4684 load impedance below  $50\Omega$ . When doing this, be sure that the LMS4684 maximum current rating is not exceeded. Also, decreasing the load impedance too much can result in excessive signal distortion because the channel resistance variation with input signal voltage would then be a greater percentage of the load impedance.

If it is desired to extend the usable bandwidth of the LMS4684 while maintaining reasonable off-isolation is through the use of the circuit of Figure 19.



**Figure 19. Using the LMS4684 at higher frequencies**

### PCB LAYOUT AND THERMAL CONSIDERATIONS

Both the WSON and DSBGA packages offer enhanced board real estate savings because of their small footprints. These tiny packages are capable of handling high continuous currents because of the advanced package thermal handling capabilities.

The WSON package has the exposed die attach pad internally connected to the internal circuit GND. When this pad is soldered to copper on the PCB board according to Application Note AN-1187, the full thermal capability of the WSON package can be achieved without additional bulky heat sinks to dissipate the heat generated. The DSBGA package has a similar capability to dissipate heat through Bumps B2 and C2, which are not electrically connected. To enhance heat dissipation of the DSBGA package B2 and C2 could be connected to the GND pin through copper traces on the board.

See Application Note AN-1112 for DSBGA package considerations.

## REVISION HISTORY

Changes from Revision B (April 2013) to Revision C	Page
• Changed layout of National Data Sheet to TI format .....	<a href="#">10</a>

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LMS4684ITL/NOPB	ACTIVE	DSBGA	YZR	12	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	F09A	<a href="#">Samples</a>
LMS4684ITLX/NOPB	ACTIVE	DSBGA	YZR	12	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	F09A	<a href="#">Samples</a>
LMS4684LD/NOPB	ACTIVE	WSO	NGZ	10	1000	Green (RoHS & no Sb/Br)	SN	Level-3-260C-168 HR	-40 to 85	L4684	<a href="#">Samples</a>
LMS4684LDX/NOPB	ACTIVE	WSO	NGZ	10	4500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	L4684	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

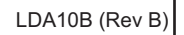
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMS4684ITL/NOPB	DSBGA	YZR	12	250	178.0	8.4	1.73	2.46	0.76	4.0	8.0	Q1
LMS4684ITLX/NOPB	DSBGA	YZR	12	3000	178.0	8.4	1.73	2.46	0.76	4.0	8.0	Q1
LMS4684LD/NOPB	WSO	NGZ	10	1000	178.0	12.4	4.3	3.3	1.0	8.0	12.0	Q1
LMS4684LDX/NOPB	WSO	NGZ	10	4500	330.0	12.4	4.3	3.3	1.0	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



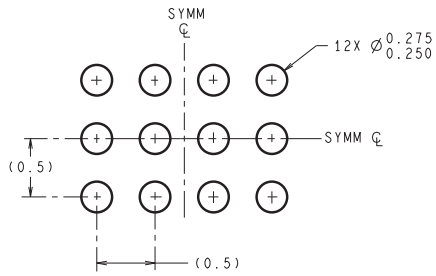
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMS4684ITL/NOPB	DSBGA	YZR	12	250	210.0	185.0	35.0
LMS4684ITLX/NOPB	DSBGA	YZR	12	3000	210.0	185.0	35.0
LMS4684LD/NOPB	WSON	NGZ	10	1000	213.0	191.0	55.0
LMS4684LDX/NOPB	WSON	NGZ	10	4500	367.0	367.0	35.0



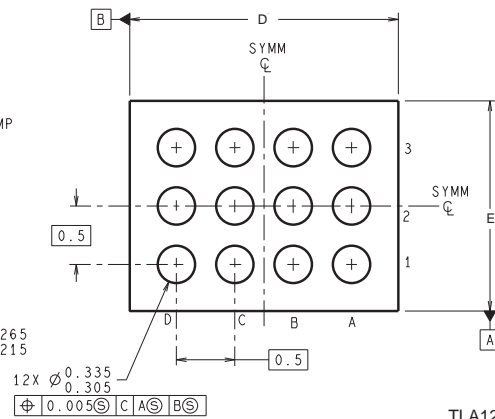
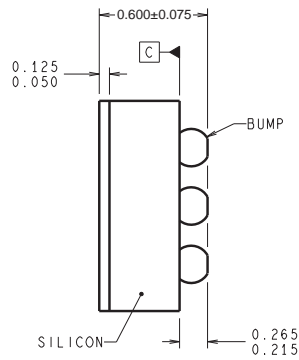
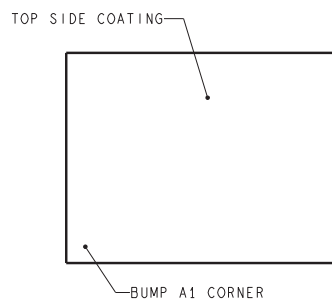


YZR0012



DIMENSIONS ARE IN MILLIMETERS  
DIMENSIONS IN ( ) FOR REFERENCE ONLY

LAND PATTERN RECOMMENDATION



TLA12XXX (Rev C)

D: Max = 2.378 mm, Min = 2.317 mm

E: Max = 1.641 mm, Min = 1.581 mm

4215049/A 12/12

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.  
B. This drawing is subject to change without notice.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)